

ABSTRACT OF THE DISCLOSURE

In an electromechanical connection between electronic circuit systems (10) and substrates (20), these components are mechanically connected fixedly to one another, their electrical connection elements (11, 21) are connected to one another in an electrically conductive manner via microcapsules (23-1, 23-2), which comprise grains (23-1) which are coated with a dielectric (23-2) and, at least in part, are electrically conductive, and there is an electrically conductive soldered joint (25 to 28) between microcapsules (23-1, 23-2) with broken-open dielectric (23-2) and the electrical connection elements (11, 21).

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